REGISTRATION

registration fees (includes coffee and sandwiches) :

□ IMAPS member (Benelux or international)	50 EUR
□ Non member workshop fee includes 2019 membership fee	120 EUR
□ Student	20 EUR
□ Student with poster	0 EUR

Registrations should be made before March 18, 2019. Cancellations after March 18 will not be refunded. After registration, you will receive a confirmation.

For table top presentation (for free) or a poster presentation, please contact :

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IMAPS - BENELUX
INTERNATIONAL MICROELECTRONICS AND PACKAGING SOCIETY
BENELUX CHAPTER

Afzender:

IMAPS-Benelux
p/a Katrien Vanneste
ELIS-CMST
Technologiepark 126
B-9052 Zwijnaarde
Belgium

IMAPS-Benelux
Spring Event
2019

Electronic packaging for green applications

Thursday, 21 March, 2019

Venue :

Energyville 1
Thor Park 8310
BE-3600 Genk

In cooperation with the Center for Electronics Design & Manufacturing

EDM
Electronic Design & Manufacturing

PROGRAM

14.00 Registration, coffee, exhibition

14.30 Green encapsulants … a continuous trend in electronics

Jochen Schuermans, Roartis, BE

Today's international trends drive towards more environmental awareness and hence, more environmental friendly consumer and/or industrial electronics. As a consequence, electronic assembly companies drive their supply chain towards the use of "greener" technologies. Governmental regulations are supporting this trend.

Our paper describes some of these latest trends in European legislation related to chemistries that may become of great concern in the future, especially for high reliability electronics. The paper will introduce some possible alternative materials for those harsh environment applications..

15.00 Low temperature solder interconnect for solar cells

Dr. N. van Veen, Mat-Tech BV, NL

For solar panels, at end of life, re-use of all materials is not possible. A panel is made such that all materials are firmly glued to each other. This only allows for 'crushing' solar panels and sorting out the remainders. By 2050, the Dutch government wants to be circular, and fulfil relevant environmental codes. This means that solar panels need to be re-designed for disassembly. As a result low temperature solder is evaluated as a reversable interconnect method for back contact panels.

15.30 Silicones for a Greener World

Herman Meynen, DowDuPont Specialty Products, BE

Silicones are widely used materials in electronic applications. In electronics packaging applications, silicones are often selected based on reliability due to the material's unique properties, which leads to longer lifetime of devices. This presentation will discuss how silicone applications enable new technologies in LEDs, micro-fluidics and others, and contribute to a greener and more sustainable world. Curing technology of silicones, which contributes to sustainability, will also be discussed..

16.00 Coffee, exhibition + opportunity to visit the imec / Energyville labs

17.00 Latest materials and technologies in cSi (crystalline Silicon) and TFPV (thin film photo-voltaic) module packaging

Aranzazu Aguirre, Energyville-imec, BE

To make crystalline silicon (cSi) modules and thin film photovoltaics (TFPV) cost competitive, special attention should be paid in finding the right balance in the cost-efficiency-lifetime triangle of photovoltaic modules. While industry is trying to push down the costs for crystalline silicon (cSi) module encapsulation, the young TFPV are now demonstrating lifetime objectives in order to enter their own niche market. We will present our latest achievements in packaging photovoltaic modules in both technologies for standard and integrated PV modules.

17.30 Current sensors for an electrified present and future

Tim Vangerven, Melexis Technologies, BE

Electric current is omnipresent in our daily lives: It is used in house appliances, in industrial manufacturing, and is strongly growing in mobility applications. The current flow of all these applications needs to monitored for optimal usage. One method of measuring current is using hall based sensors, where the output signal can be correlated to current flow, either via a non-integrated or integrated package solution. The evolution and technical challenges faced with these types of current sensors will be highlighted.

18.00 Sandwiches

19.00 Closing